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INTERNATIONAL STANDARD

Packaging of components for automatic handling – Part 3-1: Packaging of surface mount components on continuous tapes – Type V – Pressed carrier tapes

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING -

Part 3-1: Packaging of surface mount components on continuous tapes – Type V – Pressed carrier tapes

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International Standard IEC 60286-3-1 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

The text of this standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 40/1972/FDIS | 40/1981/RVD |

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

IEC 60286-3-1 is to be used in conjunction with IEC 60286-3.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all parts of the IEC 60286 series, under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING -

Part 3-1: Packaging of surface mount components on continuous tapes – Type V – Pressed carrier tapes

INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packing for components for test purposes and other operations.

This International Standard describes a carrier tape comprising concave cavities formed by compression of bulk carrier material. This specification is for size 1608 and smaller.

1 General

1.1 Scope

This part of IEC 60286 is applicable to the taping of surface mount components using carrier tapes which have concave cavities ed by compression of the base material.

1.2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60286-3:2007, Packing of components for automatic handling – Part 3: Packing of surface mount components on continuous tapes

2 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60286-3, as well as the following, apply.

2.1

pressed carrier tape

carrier tape with concave cavities formed by compression of the base material

2.2

fluff

fibre from the base material attached inside the cavity

2.3

burr

surface projection of tape unintentially produced when cavity is formed

2.4

deformation

bulge on the inner wall of the cavity

2.5 puff bulge on the reverse side of the cavity



Figure 3 – Maximum allowed pocket offset



Figure 4 – Maximum component tilt, rotation and lateral movement

()

| Table 1 – Constant | dimensions of § | mm | presse | d carrier tape |
|--------------------|-----------------|-----|--------|----------------|
| | |) T | | VIEW |

| | | | X XX X | $\langle \langle \rangle \rangle$ | \sim | | | | |
|-----------|--------------------------|----------------|------------------|-----------------------------------|--------------|------------------|---------|----------------------------------|---------------------------------------|
| Tape size | D ₀ | E ₁ | G _{min} | Po | | T _{max} | T 1 max | T ₃ -T _{max} | Cumulative pitch (over 10 pitches) |
| mm | mm | mm | mm | mm | \mathbf{i} | mm | mm | mm | mm |
| 8 | 1,5 ^{+0,1} 0 | 1,75 ± 0,1 | 0,75 | 4,0± |),1 |) 1,1 | 0,1 | 0,1 | ±0,1 |

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Table 2 – Variable dimensions of 8 mm pressed carrier tape

| Tape size | C _{max} . | E _{2 min} | F | P ₁ | P ₂ | W | A_0, B_0, K_0 | |
|--|--------------------|--------------------|--------------|----------------|----------------|-----------------------------|-----------------|--|
| mm | mm | mm | mm | mm | mm | mm | mm | |
| 8 | 4,35 | 6,25 | $3,5\pm0,05$ | 2,0 ± 0,05 | $2,0\pm0,05$ | 8,0 ^{+0,3} _0,1 | see NOTE | |
| NOTE The nominal dimensions of the component compartment should be derived from the relevant component specification. The tolerances on the nominal sizes of the compartment should be selected so that the components | | | | | | | | |

specification. The tolerances on the nominal sizes of the compartment should be selected so that the components cannot change their orientation within the tape and can be easily removed from the tape, with the following characteristics.

There should be sufficient clearance surrounding the component so that

a) the component does not protrude above the top surface of the carrier tape,

- b) the component can be removed from the cavity in a vertical direction without mechanical restriction after the top cover tape has been removed,
- c) the rotation of the component is limited to a 20° maximum tilt (see Figure 2, sketch A) and a 20° maximum planar rotation (see Figure 3, sketch B),
- d) the maximum lateral movement allowed is 0,3 mm except for 1005M sized components where the maximum should be 0,20 mm and for 0603M sized components the maximum should be 0,12 mm (see Annex A).

For defined component positioning, the pocket positions should be defined to an origin point. This origin is the centre of the index hole, defined by the crosshair of the dimensions E_1 and P_0 . The centre of the component compartment is defined by P_2 and F, relative to the sprocket hole, as shown in Figure 2 with tolerances given in the table above.

Preferred dimensions for components should be taken from the relevant IEC specifications.

Dimensions $A_0 \leq B_0$, unless otherwise specified in the component detail specification.

For components with size designation of 1005M or smaller, the puff $(T_3 - T)$ should be limited to 0,05 mm maximum.

If positioning precision is required, for example when components \leq size 1005M are mounted in narrow space, then the tolerance on D_0 should be (+0,05 / 0,00) mm.

4 Polarity and orientation of components in the tape

Requirements shall be in accordance with IEC 60286-3, 4.1, 4.2.1 and 4.2.3.

5 Fixing of components and additional tape requirements

Requirements shall be in accordance with IEC 60286-3, 5.1, 5.2, 5.4, 5.5, 5.6, 5.7 and 5.8 and the following.

5.1 Specific requirements for Type V tapes

5.1.1 Minimum bending radius

The minimum bending radius (R_{\min}) shall be 25 mm.

5.1.2 Measurement method for carrier tape thickness (T and T_3)

The equipment used to conduct these measurements shall be an external micrometer with a measuring pressure of 1,5 N or smaller. The probe shall be made of super-hard material and the diameter of the probe head shall be 2,0 mm.